

Customer Information Notification

18-Aug-2018 Issue Date: Effective Date: 19-Aug-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

2018080181



Management Summary

Increase of die thickness from 250um to 280um for low voltage controller and medium voltage d	Increase	of die	e thickness	from 250um to	280um for	low voltage	controller	and medium	voltage /	die
---	----------	--------	-------------	---------------	-----------	-------------	------------	------------	-----------	-----

C)	h	a	n	g	е	C	at	te	g	0	ry	

,	[] Product Marking	[] Test	[] Design
	FIM. de disello de difference		F 1 =
,	[] Mechanical Specification	ı[]rest	[] Errata
Materials		Process	
[] Assembly	[]	[]Test	[] Electrical
Location	Packing/Shipping/Labeling	Equipment	spec./Test
			coverage
	Process [] Assembly Materials [] Assembly	[] Assembly [] Mechanical Specification Materials [] Assembly []	Process Location [] Assembly [] Mechanical Specification[]Test Materials Process [] Assembly [] [] Test

[] Other [] Firmware

TEA19051 Die Thickness Increase

Description

NXP announces the increase of die thickness from 250um to 280um for low voltage controller and medium

No change in: waferfab process, die design & layout, package outline, datasheet, 12NC number, product performance & functionality and application sheet.

Qualification completed and PQIP updated.

Reason

Standardization in manufacturing.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

No change in: waferfab, die design & layout, package outline, datasheet, 12NC number, product performance & functionality and application sheet.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Jason Chen

Position Customer Quality Engineer e-mail address jason.cj.chen@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they

reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

NXP | Privacy Policy | Terms of Use

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.

Changed Orderable Part# Changed Part 12NC Changed Part Number Changed Part Description Package Outline Package Name Status Product Line
TEA19051BAATK/1J 935361506118 TEA19051BAATK/1 SmartCharg Protoc contr QC4 SOT1308-2 HVSON16 RS BLSECURE INTERFACES & POWER